

Application No.: 10/901,500

Docket N .: JCLA7208

In The Specification:

Please amend the abstract as follows:

B2
A method of laminating copper foil onto a substrate of a printed circuit board, wherein the substrate has an upper surface and a lower surface. Isolating material is coated onto both surfaces of the substrate to form isolating layers on the substrate. The isolating layers can be formed by roll coating, spray coating or screen printing. The thickness of the isolating layers can be controlled in accordance to the requirements of the circuits. Various types of metal foils can be laminated onto the ~~adhesive~~ isolating layers, followed by heating and pressurization processes to secure the metal foil onto the substrate.

In The Drawings:

Please amend Fig. 1a and Fig. 1b by adding the legend "PRIOR ART" as shown in the attached sheet.